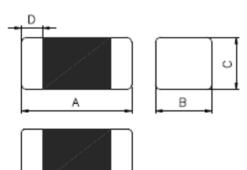


## **FEATRLRES**

- Monolithic inorganic material construction.
- Closed magnetic circuit avoids crosstalk.
- S.M.T. type.
- Suitable for reflow soldering.
- Shapes and dimensions follow E.I.A. spec.
- Available in various sizes.
- Excellent solder ability and heat resistance.
- High reliability.
- 100% Lead(Pb) & Halogen-Free and RoHS compliant.

## CONFIGRLRATIONS & DIMENSIONS ( unit in mm )



Size	Α	В	С	D
HCB4516	4.5±0.2	1.6±0.2	1.6±0.2	0.5±0.3

### **ELECTRICAL CHARACTERISTICS**

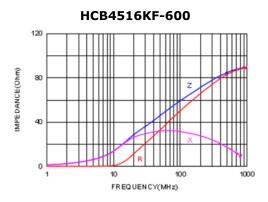
Number	Impedance (Ω)	Test Frequency	DC Resistance ( $\Omega$ )	Rated Current (mA)
		(MHz)	max.	max.
HCB4516KF-600T60	60±25%	60mV/100M	0.01	6000
HCB4516KF-800T30	80±25%	60mV/100M	0.04	3000

Rated current: based on temperature rise test

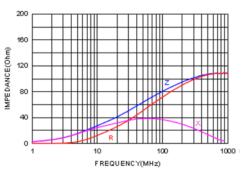
■ In compliance with EIA 595



# Impedance Frequency Characteristics(Typical)



#### HCB4516KF-800



## **Reliability and Test Condition**

ltem	Performance	Test Condition
Operating temperature	-40~+125°C (Including self - temperature rise)	
Storage temperature	110~+40℃,50~60%RH (Product with taping) 240~+125℃(on board)	
Electrical Performance Test		
Inductance	Refer to standard electrical characteristics list.	HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter.
DCR		CH16502, Agilent33420A Micro-Ohm Meter.
Saturation Current (Isat)	Approximately∆L30%	Saturation DC Current (Isat) will cause L0 to drop $\ \triangle L(\%)$
Heat Rated Current (Irms)	Approximately △T40℃	Heat Rated Current (Irms) will cause the coil temperature rise $\triangle T(^{\circ}C)$ . 1.Applied the allowed DC current 2.Temperature measured by digital surface thermometer
Reliability Test		
Life Test		Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles) Temperature : 125±2℃(Inductor) Applied current : rated current Duration : 1000±12hrs Measured at room temperature after placing for 24±2 hrs
Load Humidity	Appearance : No damage.	Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles Humidity : 85±2 * R.H, Temperature : 85℃±2℃ Duration : 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs
Moisture Resistance	Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	<ul> <li>Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles</li> <li>1. Baked at50°C for 25hrs, measured at room temperature after placing for 4 hrs.</li> <li>2. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs.</li> <li>3. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in</li> <li>2.5hrs, keep at 25°C for 2 hrs then keep at -10°C for 3 hrs</li> <li>4. Keep at 25°C 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.</li> </ul>



Thermal shock Vibration		Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD- 020DClassification         Reflow Profiles         Condition for 1 cycle         Step1 : -40±2°C 30±5min         Step2 : 25±2°C ≤0.5min         Step3 : 125±2°C 30±5min         Number of cycles : 500         Measured at room temperature after placing for 24±2 hrs         Oscillation Frequency: 10 ~ 2K ~ 10Hz for 20 minutes         Equipment : Vibration checker         Total Amplitude:1.52mm±10%         Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations).
Bending		Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm <0805 inch(2012mm):40x100x0.8mm Bending depth: >=0805 inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.
Shock	Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	TypePeak value (g's)Normal duration (D) (ms)Wave formVelocity change (Vi)ft/secSMD5011Half-sine11.3Lead5011Half-sine11.3
Solder ability	More than 95% of the terminal electrode should be covered with solder.	Preheat: 150°C,60sec.。 Solder: Sn96.5% Ag3% Cu0.5% Temperature: 245±5°C 。 Flux for lead free: Rosin. 9.5% 。 Dip time: 4±1sec 。 Depth: completely cover the termination
Resistance to Soldering Heat		Depth: completely cover the termination       Temperature ramp/immersion and emersion rate     Number of heat cycles       260 ±5 (solder temp)     10 ±1     25mm/s ±6 mm/s     1
Terminal Strength	Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value e	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD- 020DClassification Reflow Profiles With the component mounted on a PCB with the device to be tested, apply a force(>0805:1kg, <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.

Note : When there are questions concerning measurement result : measurement shall be made after  $48 \pm 2$  hours of recovery under the standard condition.